Industry Case Studies Program – Industry Day

Industry Applications and Standard initiatives for Cooperative Information Systems:
The evolving role of Cyber Physical Systems in Industry 4.0 implementation

http://www.otmconferences.org/index.php/industry-2018

October, 23rd, 2017, Valletta, Malta

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Object management Group (OMG) (http://www.omg.org)
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Cooperative Information Systems provide enterprises and communities of users with flexible, scalable and intelligent services in large-scale networking environments. The OTM conference series has established itself as a major international forum for exchanging ideas and results on scientific research for practitioners in fields such as computer supported cooperative work (CSCW), middleware, Internet/Web data management, electronic commerce, workflow management, knowledge flow, agent technologies and software architectures, to name a few. The recent popularity and interest in service-oriented architectures & domains require capabilities for on-demand composition of services. Furthermore, cloud computing environments are becoming more prevalent, in which information technology resources must be configured to meet user-driven needs. These emerging technologies represent a significant need for highly interoperable systems. This edition will address a particular set of topics and applications related to Interoperability for Cyber Physical Systems.

As a part of OnTheMove 2018, we are organizing an Industry Case Studies Program. The objective is to take industrial viewpoints to shape the collaboration between research and industry and look at ways to bring the research to market and support future collaboration or project definition. The focus of the program is to facilitate discussions between peers and to enhance research focus on interoperable information systems to enable Industry 4.0 implementation. Other discussion topics include Enterprise transformation, assessment and improvement, architecture development to aid interoperability and infrastructure design.

Industry leaders, standardisation initiatives, European and international projects consortia are invited to present their ongoing or past projects for follow ups or the involvement of the community as well as discuss about new/immature ideas to brainstorm and build up new projects. Three kinds of submissions are welcomed:
- **Paper-oriented submission**: This may discuss industrial experience or academic research and should not exceed 4 pages in the final camera-ready format.
- **Project-oriented submission (abstract)**: This may present an ongoing project or an innovative idea of a project to build and should not exceed 2 pages in the final camera ready format.
- **Networking-oriented/brainstorming-oriented submission**: This may be a presentation of a past or an ongoing project as well as a project idea to discuss.

All submissions will be reviewed by at least three members of the Program Committee, based on their originality, significance, technical soundness, and clarity of expression. Submissions must be in English. Only electronic submissions in Adobe PDF format are acceptable.

The final proceedings will be published by Springer Verlag as LNCS (Lecture Notes in Computer Science). Author instructions can be found at:

[http://www.springer.de/comp/lncs/authors.html](http://www.springer.de/comp/lncs/authors.html)

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**YOU CAN ALSO HAVE A LOOK AT:**

All authors can also benefit from the participation to the panel that will occur at the end of the session.

**IMPORTANT DATES**

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<th>Date</th>
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<tr>
<td>Short Paper Submission Deadline</td>
<td>July 31th, 2018</td>
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<tr>
<td>Acceptance Notification</td>
<td>August 20th, 2018</td>
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<tr>
<td>Camera Ready Due</td>
<td>August 30th, 2018</td>
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<tr>
<td>Registration Due</td>
<td>September 1st, 2018</td>
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<td>OTM Conferences</td>
<td>October 22-26, 2018</td>
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<td>Updated Camera-ready upload (optional):</td>
<td>December 1st, 2018</td>
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For more information, please send a short abstract to the Program Chairs.

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The program committee is composed of representatives of industry, standard initiatives and European or international R&D projects

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